

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC9252xxxxDR-G
Typical Mass: 12 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.923	Silicon	76900	7440-21-3
	-	Arsenic	<1	7440-38-2
Lead pad	2.831	Nickel	236000	7440-02-0
	0.223	Silver	18600	7440-22-4
	0.042	Gold	3500	7440-57-5
Die attach	0.042	Epoxy Resin	3500	—
	0.036	Silica	3000	60676-86-0
Bonding wire	0.076	Gold	6300	7440-57-5
Resin	7.045	Silica	587100	60676-86-0
	0.431	Epoxy Resin	35900	—
	0.352	Phenol Resin	29400	—

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."